

ACT1x5, 2x6 & 3x8 Watch Crystal

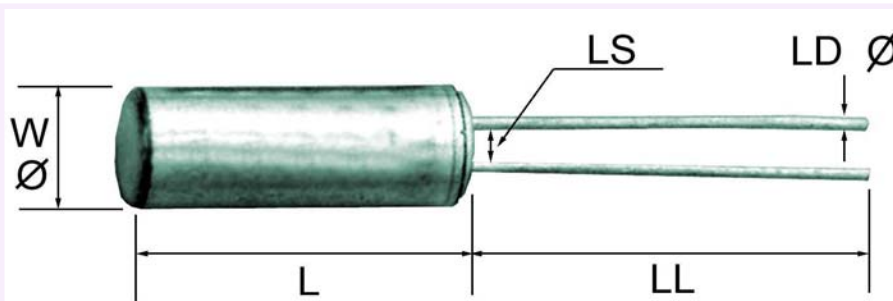


The ACT1x5, 2x6 & 3x8 are miniature cylindrical packages offering high vibration and shock resistance, together with high stability. They are suitable for portable equipment and where a close packing density is required. Two versions are offered, C1BLC: a low cost version and the HQM4E: a version with a higher Q value. The 1x5 device is only available in the High Q version.



Specification

Parameter	Specification	C1bLC Series		HQM4E Series		
		3x8	2x6	1x5	2x6	3x8
Nominal Frequency	fo	32.768KHz				
Outline		3x8	2x6	1x5	2x6	3x8
Quality Factor (Typical)	Q	60,000	50,000	85,000	70,000	85,000
Shunt Capacitance (Typical)	C0	1.8pF	1.45pF	1.0pF	1.35pF	1.6pF
Equivalent Series Resistance	ESR	30KΩ max	35KΩ max	40KΩ max	35KΩ max	
Motional Capacitance (Typical)	C1	0.0030pF	0.0028pF	0.0024pF	0.0024pF	
Frequency Tolerance @25°C	Δf/fo	±20ppm standard ±5, ±10ppm options)		±20 standard	±20ppm standard (2x6 & 3x8: ±5 & ±10ppm options)	
Load Capacitance	CL	6pF~12.5pF(6, 12.5pF standard		12.5pF	12.5, 6.0pF	
Frequency v Temperature	Δf/tamb	See Drawing -40 °C +85°C		See Drawing (-40 °C +85°C)		
Turnover Temperature	Tm	25°C ±5°C		25°C ±5°C		
Temperature Coefficient	β	-0.035±0.0086ppm / °C ²		-0.034+/-0.006ppm / °C ²		
Temp Operating Range	Topr	-10 +60°C standard , (-20~+70, -40 +85°C Options)		-20 +70°C ,(-40 +85°C option)		
Temp Storage Range	Tstg	-40 ~ +85°C		-40~+85°C		
Drive Level	DL	1μ W max		1μ W max		
Insulation Resistance	IR	500MΩ / 100VDC min		500MΩ / 100VDC min		
Aging	Δf/yr	±5ppm First year, 25°C (±3ppm option)		+/-3ppm(25°C 1st year)		
Shock Resistance	Δf/shock	±5ppm		±5ppm		



		DIMENSIONS (mm)					
		L	W	LL	LD	LS	
C1bLC HQM4E	2x6	6.0 +0.3/-0.2	2.0 +/-0.1	7 +/-0.3	0.20 +/-0.06	0.7 +/-0.15	
		6.0 +/-0.2	2.0 +/-0.1	10 +/-0.2	0.26 +/-0.05	0.7 +/-0.2	
C1bLC HQM4E	3x8	8.0 +0.3/-0.2	3.0 +/-0.1	9.6 +/-0.3	0.30 +/-0.01	0.8 +/-0.15	
		8.0 +/-0.2	3.1 +/-0.1	10 +/-0.2	0.35 +/-0.04	1.1 +/-0.2	
HQM4E	1x5	5.0 +/-0.1	1.4 +/-0.1	4.3 +/-0.3	0.20 +/-0.05	0.45 +/-0.08	

Soldering

Lead wire should be soldered within 10 seconds with a tip temperature not exceeding 270°C. The device should ideally be upright on the board. If the device can is required to be mechanically affixed to the board it should be stuck down with rubber adhesive. Under no circumstances should any solder connection be made to the can of the device.

Please note that all parameters can not necessarily be specified in the same device

Customer To specify : Frequency Tolerance, Load Capacitance, Operating Temperature Range

In line with our ongoing policy of product evolution and improvement, the above specification may be subject to change without notice

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For quotations or further information please contact us at:

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